



VMDSEMI

**VUSG002R750PA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
-20V	75mΩ@-4.5V	-1.4A
	105mΩ@-2.5V	
	156mΩ@-1.8V	

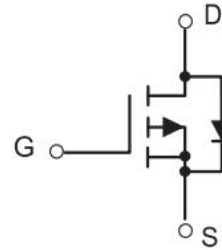


Figure 1 Symbol of VUSG002R750PA

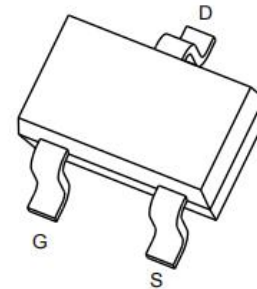
## Features

- Leading Trench Technology for Low  $R_{DS(on)}$
- Extending Battery Life

## Package Type

## Application

- High Side Load Switch
- Charging Circuit
- Single Cell Battery Applications



## SOT-323

Figure 2 Package Type of VUSG002R750PA

## Ordering Information

Product Name	Package
VUSG002R750PA	SOT-323

**Absolute Maximum Ratings** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	-20	V
Gate-Source Voltage	$V_{GSS}$	$\pm 8.0$	V
Continuous Drain Current <sup>Note1,2</sup>	$I_D$	-1.4	A
Pulsed Drain Current	$I_{DM}$	-5.6	A
Total Power Dissipation <sup>Note1</sup>	$P_D$	0.57	W
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note1,2</sup>	$R_{\theta JA}$		220		$^\circ\text{C}/\text{W}$

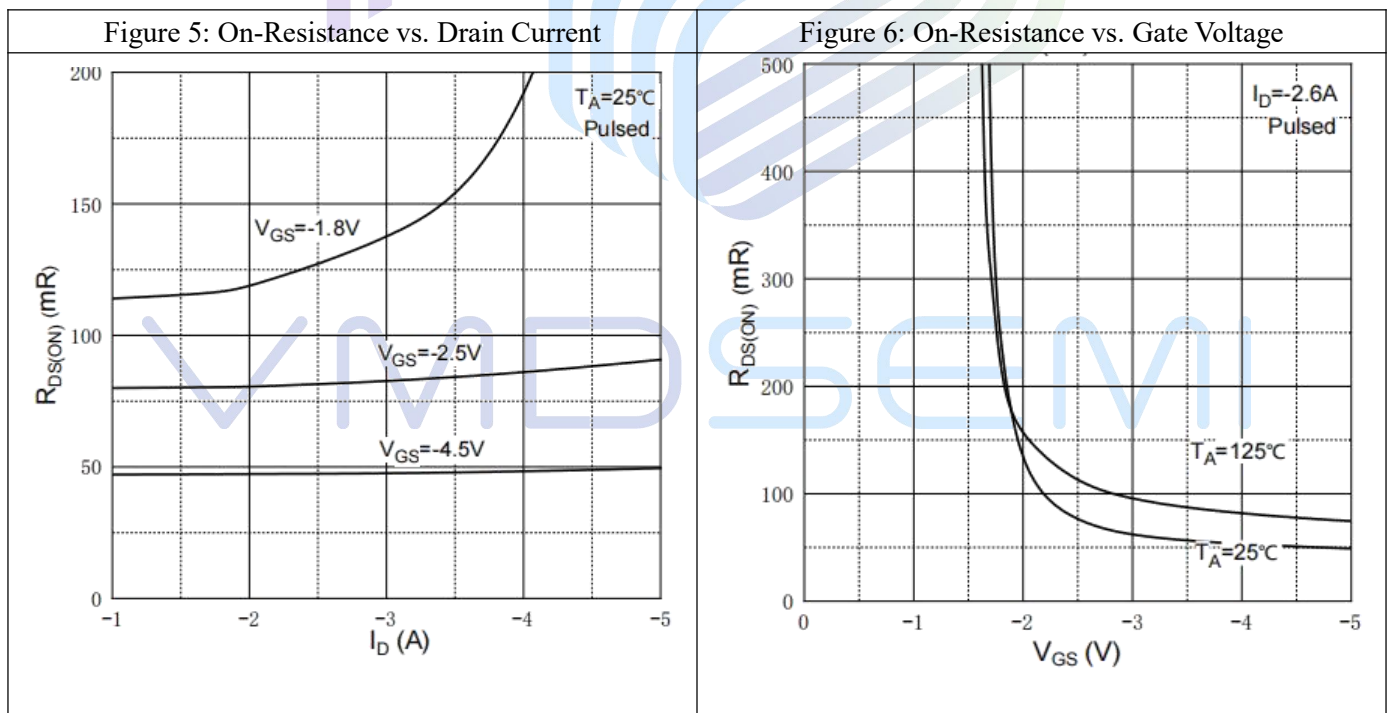
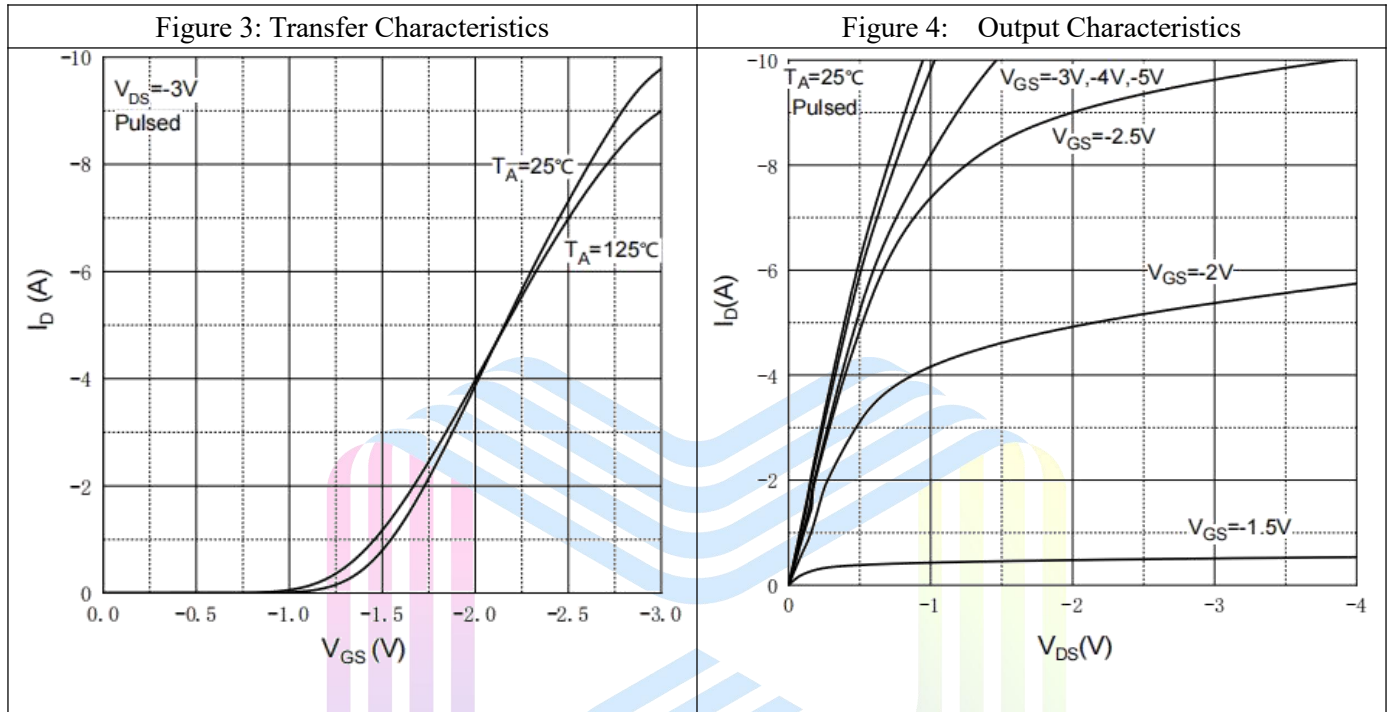


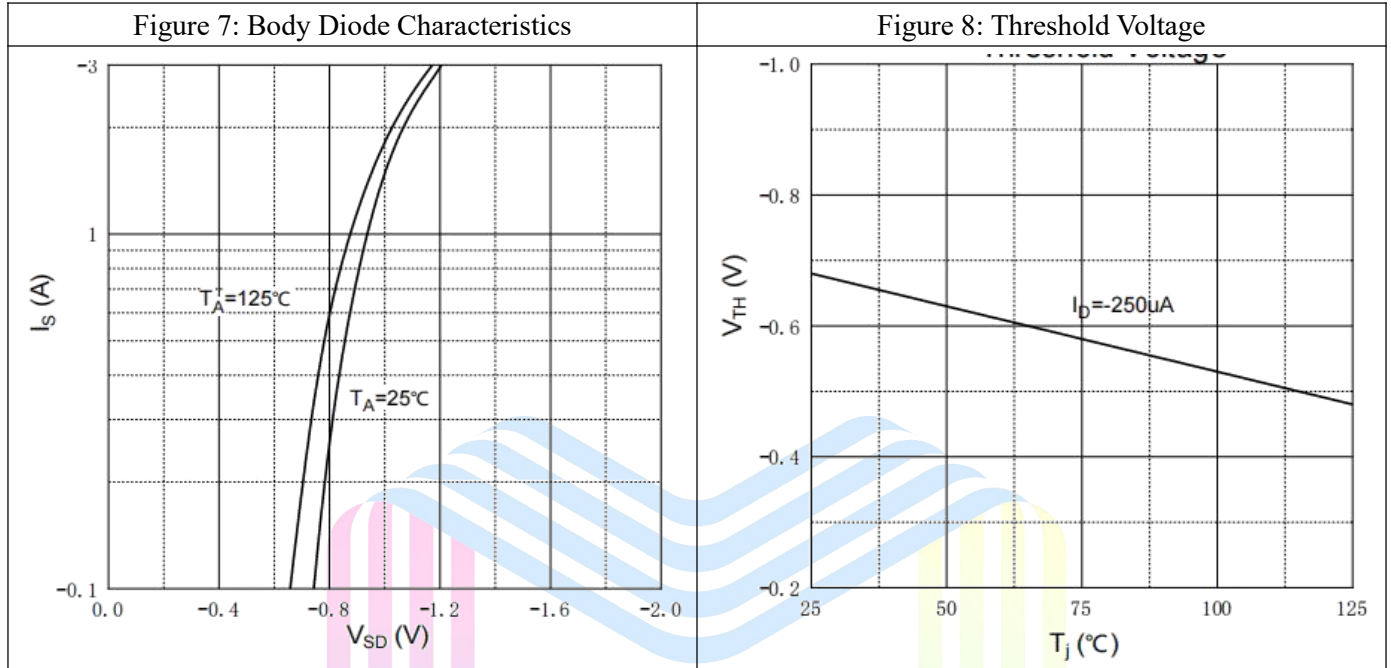
**Electrical Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D = -250\mu A$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -16V, V_{GS}=0V$			-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 8V, V_{DS} = 0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1.0	V
Static Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -1.0A$		50	75	mΩ
		$V_{GS} = -2.5V, I_D = -0.5A$		70	105	
		$V_{GS} = -1.8V, I_D = -0.3A$		115	156	
Forward tranconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS} = -5V, I_D = -0.8A$	8			S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS} = -10V$		350		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		75		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		67		pF
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{DS} = -10V$		8.2		nC
Gate-source Charge	$Q_{gs}$	$V_{GS} = -4.5V$		1.1		
Gate-drain Charge	$Q_{gd}$	$I_D = -1.4A$		2.0		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -10V$		7.0		ns
Turn-on Rise Time	$t_r$	$V_{GS} = -4.5V$		32		
Turn-off Delay Time	$t_{d(off)}$	$I_D = -1.4A$		49		
Turn-off Fall Time	$t_f$	$R_G = 3\Omega$		55		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	$V_{SD}$	$V_{GS}=0V, I_S = -0.3A$			-1.2	V

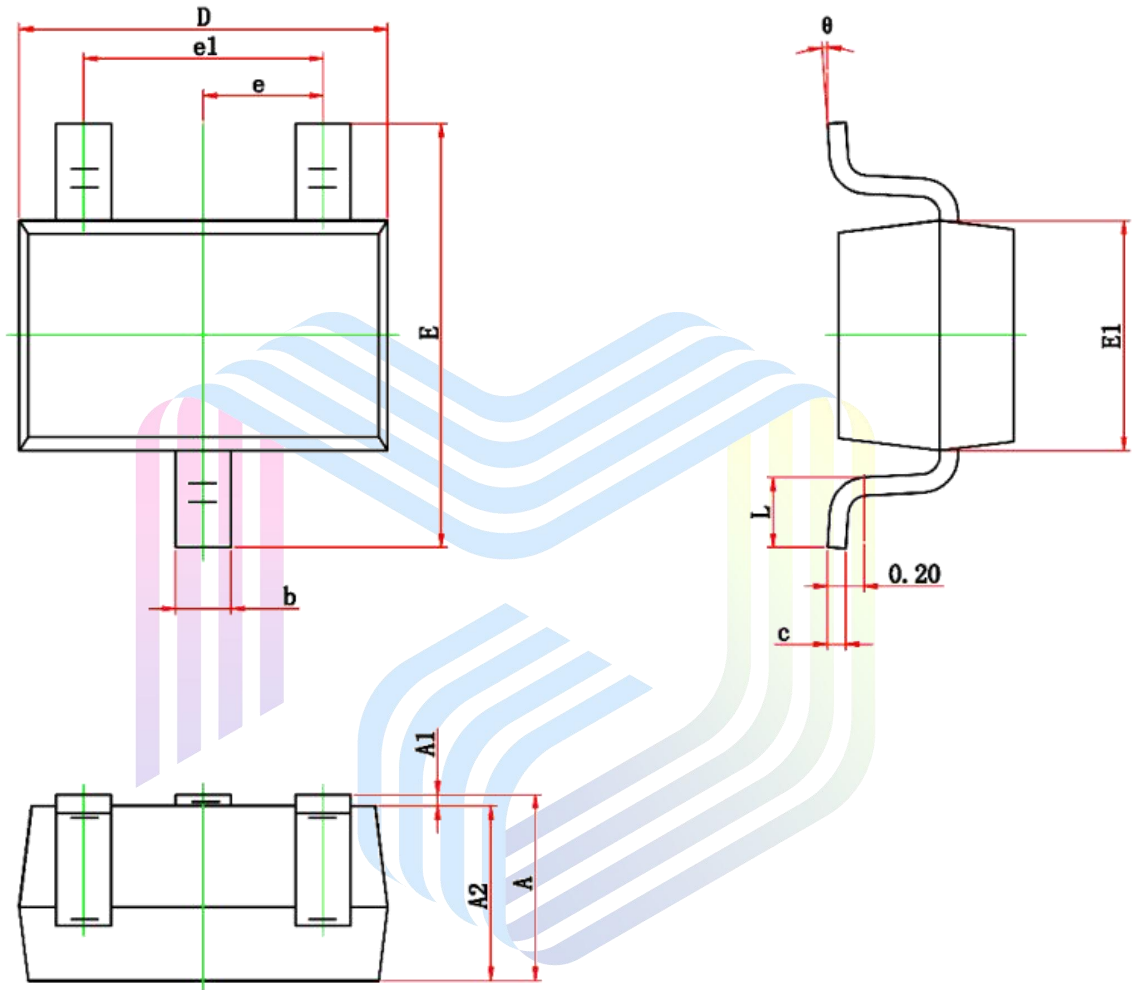
**Notes :**

- $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR4 board with 1oz. single side copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .
- $R_{\theta JA}$  is measured in the steady state
- Pulse test : Pulse width  $\leq 380\mu s$ , duty cycle  $\leq 2\%$ .

**Typical Performance Characteristics**




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**Mechanical Dimensions:**
**SOT-323 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.050	0.150	0.002	0.006
D	1.900	2.200	0.075	0.087
E	2.000	2.450	0.079	0.096
E1	1.150	1.350	0.045	0.053
e	0.650TYP.		0.026TYP.	
e1	1.200	1.400	0.047	0.055
L	0.200	0.460	0.008	0.018
θ	0°	8°	0°	8°

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